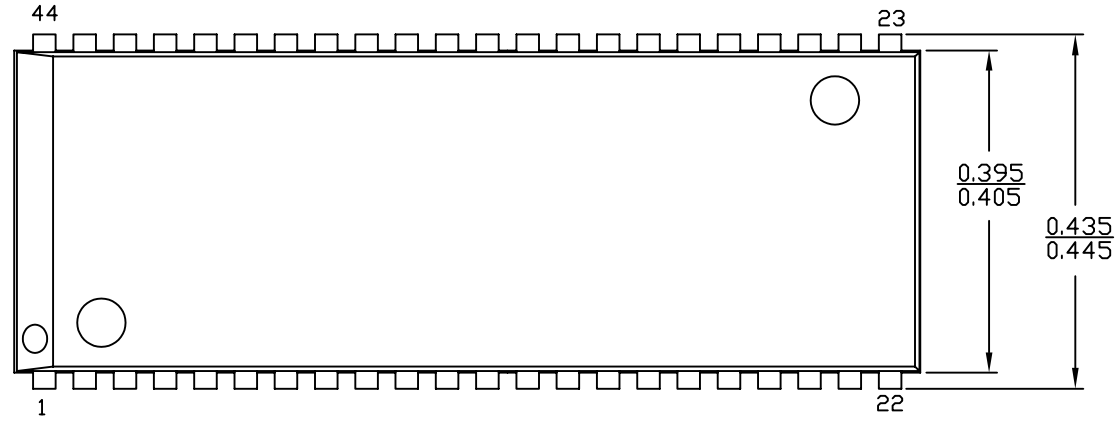


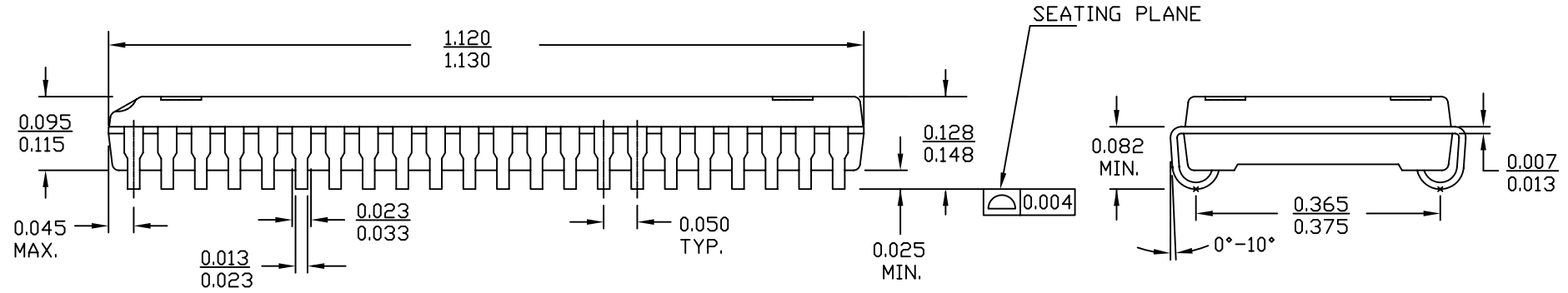
REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	43728	NEW RELEASE	07/17/96	N/A
1	-	*A	49485	CHG. TITLE	05/29/97	N/A
1	-	*B	54476	CHG. PKG HEIGH & LEAD WIDTH	02/09/98	N/A
1	-	*C	2833453	Changed template, & title from 44LD (400 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 44LD SOJ 400 MILS V44.4.	12/28/09	QAD
1	-	*D	3352935	Update spec for sunset review, no changed	08/24/11	QAD
1	-	*E	3726137	Sunset Review, Added Package Weight - Refer to PMDD spec.	08/28/12	QAD


44 Lead (400 MIL) MOLDED SOJ



DIMENSIONS IN INCHES MIN. MAX.

Package Weight - Refer to PMDD spec.



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:		DESIGNED BY HTN	DATE 02/09/98	 CYPRESS Company Confidential
DECIMALS .XX ± 0.05 .XXX ± .XXXX +	ANGLES ± 1°	DRAWN BY ROWI	DATE 08/28/12	
		CHECKED BY QAD	DATE 08/28/12	TITLE PACKAGE OUTLINE, 44LD SOJ 400 MILS V44.4
		APPROVED BY EDCA	DATE 08/28/12	SIZE A
MATERIAL N/A		APPROVED BY QAD	DATE 08/28/12	PART NO. V44.4
FINISH N/A		APPROVED BY NA	DATE NA	DWG NO 51-85082
		SCALED TO FIT		REV *E
		N/A		SHEET 1 OF 1

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